



Flexible Electronic Materials and Devices: Preparation and Application

Guest Editor:

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Message from the Guest Editor

Dear Colleagues,

Flexible electronics have advanced significantly in the past decade, enabling their application in numerous domains where conventional rigid electronics cannot be applied, such as bioelectronics and electronic sensors, etc. Two main strategies have been proposed to introduce flexibility in electronic materials: reducing the thickness of commercially available inorganic semiconductor materials and designing novel semiconductor materials with intrinsic mechanical flexibility. Further advances in flexible electronic devices would require the matrimony of material synthesis, device physics and engineering, and advanced characterization expertise to enable the development of high-performance devices with decent reliability for practical real-world applications.

This Special Issue aims to compile research papers, short communications, and review articles focused on the synthesis of novel materials, device design, fabrication, and the advanced characterization of various flexible electronic devices for the identification of the main milestones in the roadmap of future flexible electronics research.





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Message from the Editor-in-Chief

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